



Instructions: Both partners applying for the program should fill this form in together and submit it to the two counterpart agencies. Please include along with this form a signed letter of intent (LOI) outlining the IP plans, as well as resumes/CVs of key personnel.

1. (1. General Information							
1.1	Project Title	(Do not exceed 120 c	characters)					
1.2	Submission Date							
	_							
1.3	Summary	(Do not exceed 240 c	characters)					
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1. 4 I	Fechnology Sector & Su Clean-Tech	ubsector of Project (Se	elect I sector and I corre	sponding subsector)				
Ш		П г	Environment	Materials				
	Agrobiotech	Energy	Environment	Materials				
	Water Technologies							
	Communications							
	Broadband Access	Broadcast	Enterprise Networking	Home Networking				
	Mobile Applications	NGN & Convergence	Optical Networking	Telecom Applications				
	VoIP & IP Telephony	Wireless Applications	Wireless Infrastructure					
	Internet							
	Content Delivery	Content Management	e-Commerce	E-Learning				
	Internet Applications	Internet Infrastructure	Online Advertising	Online Entertainment				
	Search Engines	Social Networks						
Ш	IT & Enterprise Softwar							
	Business Analytics Miscellaneous Software	Cyber Security	Enterprise Applications	Enterprise Infrastructure				
		Design and Development	L TOOIS					
	Life Sciences							
	Agrobiotech	Bioinformatics	Biologicals Madical Basissas	Diagnostics				
	Healthcare IT Therapeutics	Industrial Neuroscience	Medical Devices	Telemedicine				





Miscellaneous To	echnologi	es			
Defense Nanotechnology		Hardware	Industrial Techn	nologies	cellaneous
Semiconductors					
Fabrication and		Manufacturing	Memory & Stora	nge Miso Semicon	cellaneous nductors
Network Process	_	Processors & RFID	Security Semico	nductors Uide	eo, Image & Audio
1.5 Participants' Con	ntribution	ıs			
Company Name	Country	Role of Participant	Contribution (%)	Budget (\$US)	Duration (Months)
Total:					
1.6 Start Date:			End Date:		





2. Project Outline
2.1 Project Description





2.2 Technological Development Envisaged (Level of Innovation)	





2.3 Market Potential and Commercialization Plan
2.4 Cooperation between Participants (Synergies, advantages, complementarities, etc.)
2.5 Expected Outcome of Project
2.6 IP Ownership Agreement
Plance attach a congrate cianed "letter of intent"
Please attach a separate signed "letter of intent"





3. Project Participant	s – Par	tner 1			
3.1. Participant Profile 3.1.1 General Profile Full Name of Company				Registration #	
Prior name of Company					
Type of Company	□нт	□R&D	Rese	earch Institute 🗌	University Other
Stage	Seed		R&D	☐Initial Revenue	s Revenue Growth
Ownership	Public		Private	Governmental	Other
Year Established				No. Employees	
No. R&D Personnel]	
3.1.2 Company Conta Street Address	ct Info				
City				P.O. Box	
Country				Zip Code	
Telephone				Fax	
Website				E-mail	
3.1.3 Contact Person					
First Name				Last Name	
Title				Function	
Phone				Mobile Phone	
Email					





General Business Description & Area of Expertise
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Technology Description (Main Products/Services)
Targeted Customers
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IP
Sales (for last 3 years) Current year (i) i-1 i-2
carrent year (i)
Comments





3.1.5 Technology Sector & Subsector of Company (Select 1 Sector and 1 Subsector)							
Clean-Tech			_				
Agrobiotech	Energy	Environment	Materials				
Water Technologies							
Communications							
Broadband Access	Broadcast	Enterprise Networking	Home Networking				
Mobile Applications	NGN & Convergence	Optical Networking	Telecom Applications				
VoIP & IP Telephony	Wireless Applications	Wireless Infrastructure					
Internet							
Content Delivery	Content Management	e-Commerce	E-Learning				
Internet Applications	Internet Infrastructure	Online Advertising	Online Entertainment				
 Search Engines	Social Networks						
IT & Enterprise Softwar	re						
Business Analytics	Security	Enterprise Applications	Enterprise Infrastructure				
 Miscellaneous Software	Design and Development	Tools					
Life Sciences							
Agrobiotech	Bioinformatics	Biologicals	Diagnostics				
Healthcare IT	Industrial	Medical Devices	Telemedicine				
 Therapeutics							
Miscellaneous Technolo	ogies						
Defense	Hardware	Industrial Technologies	Miscellaneous				
 Nanotechnology							
Semiconductors							
Fabrication and Testing	Manufacturing Equipment & EDA	Memory & Storage	Miscellaneous Semiconductors				
 Network Processors	Processors & RFID	Security Semiconductors	Video, Image & Audio				





3.2 Work – Description and Contributions to the Project
·
3.3 Work Plan and Timeline
3.4 Budget and Resources
3.5 Other Sources of Financial Support Related to Proposed Research
3.5.1 Is this, or related R&D, presently being supported by other sources? If yes, indicate other sources,
amounts, and dates of performing the R&D under this support
3.5.2 Has your company previously received other sources of governmental support? If yes, list up sources and dates.
שנים בישור של היא מורכים מווע עמנכים.





4. Project Participant	s – Par	tner 2			
4.1. Participant Profile 4.1.1 General Profile Full Name of Company				Registration #	
Prior name of Company					
Type of Company	□нт	□R&D	Rese	earch Institute	University □Other
Stage	Seed		R&D	☐Initial Revenue	s Revenue Growth
Ownership	Public		Private	Governmental	☐ Other
Year Established				No. Employees	
No. R&D Personnel					
4.1.2 Company Conta Street Address	ct Info				
City				P.O. Box	
Country				Zip Code	
Telephone				Fax	
Website				E-mail	
4.1.3 Contact Person					
First Name				Last Name	
Title				Function	
Phone				Mobile Phone	
Email					





Technology Description (Main Products/Services) Targeted Customers IP Sales (for last 3 years) Current year (i) i-1 i-2 Comments	General Business Description & Area of Expertise
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Targeted Customers IP Sales (for last 3 years) Current year (i) i-1 i-2	
Targeted Customers IP Sales (for last 3 years) Current year (i) i-1 i-2	
Targeted Customers IP Sales (for last 3 years) Current year (i) i-1 i-2	
Targeted Customers IP Sales (for last 3 years) Current year (i) i-1 i-2	Technology Description (Main Products/Services)
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IP Sales (for last 3 years) Current year (i) i-1 i-2	
Sales (for last 3 years) Current year (i) i-1 i-2	Targeted Customers
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Sales (for last 3 years) Current year (i) i-1 i-2	
Sales (for last 3 years) Current year (i) i-1 i-2	
Sales (for last 3 years) Current year (i) i-1 i-2	TP
Current year (i) i-1 i-2	
Current year (i) i-1 i-2	
Current year (i) i-1 i-2	Salos (for last 3 years)
Comments	
Comments	
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	Water Technologies							
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	Life Sciences							
	Agrobiotech	Bioinformatics	Biologicals	Diagnostics				
	Healthcare IT	Industrial	Medical Devices	Telemedicine				
	Therapeutics							
	Miscellaneous Technolo	ogies						
	Defense	Hardware	☐ Industrial Technologies	Miscellaneous				
	Nanotechnology							
	Semiconductors							
	Fabrication and Testing	Manufacturing	Memory & Storage	Miscellaneous				
	Network Processors	Equipment & EDA Processors & RFID	Security Semiconductors	Semiconductors Video, Image & Audio				
	 4.1.6 Company Settings (For Israeli Companies ONLY) Would you like your company profile to appear in the public, online MATIMOP Company Database? Would you like to receive emails from MATIMOP on news & events? 							
	Would you like to receive emails from MATIMOR of flews & events:							





4.2 Work – Description and Contributions to the Project		
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4.3 Work Plan and Timeline		
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4.5.2 Has your company previously received other sources of governmental support? If yes, list up sources and dates.		
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5. Statement of Cooperation

The participants signing this form intend to co-operate within the project as described in this form with the aim realizing the technical developments as set forth under point 2. In addition the participants have or intend to put in place, a formal collaboration agreement.

5.1	Signature of Partner 1		
	Company Name		
	First Name	Last Name	
	Title	Function	
	Signature		
5.2 Signature of Partner 2 Company Name		ier 2	
	First Name	Last Name	
	Title	Function	
	Signature		